

Lecture 3: More technology

Wednesday, January 9, 2019 6:40 PM

Outline

- Energy and power of CMOS devices
- Trends in technology
- Start on ISA/instructions, if time

IF A RESEARCHER SAYS A COOL
NEW TECHNOLOGY SHOULD BE
AVAILABLE TO CONSUMERS IN...

WHAT THEY MEAN IS...

THE FOURTH QUARTER OF NEXT YEAR	THE PROJECT WILL BE CANCELED IN SIX MONTHS.
FIVE YEARS	I'VE SOLVED THE INTERESTING RESEARCH PROBLEMS. THE REST IS JUST BUSINESS, WHICH IS EASY, RIGHT?
TEN YEARS	WE HAVEN'T FINISHED INVENTING IT YET, BUT WHEN WE DO IT'LL BE AWESOME.
25+ YEARS	IT HAS NOT BEEN CONCLUSIVELY PROVEN IMPOSSIBLE.
WE'RE NOT REALLY LOOKING AT MARKET APPLICATIONS RIGHT NOW.	I LIKE BEING THE ONLY ONE WITH A HOVERCAR.

Energy and Power of CMOS devices

How do energy and power relate?

$$P = \frac{E}{\text{time}}$$

Constraints
Energy + Power

Energy =

Static energy: Constant output

Dynamic energy: Depends on switching

Static energy increases
w/ smaller transistors

dynamic

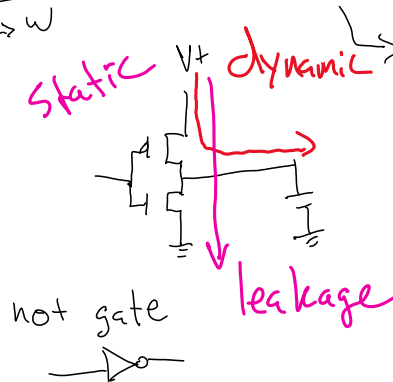
$$\text{Energy of a system} = \alpha C \cdot V^2$$

activation
transistors
switching

capacitance

Power:

Energy costs money → Battery for mobile
↳ Wh
Power → heat dissipation → mobile limited by human hand
↳ W
↳ tech to cool
fan vs fanless vs water cooling
energy to cool



dynamic Power of chip = $\alpha C V^2 \cdot f$

↑
frequency

If we are power/energy constrained: How do we reduce power/energy?

$$E = \alpha C V^2$$

$$P = \alpha C V^2 f$$

$$E = P \cdot t$$

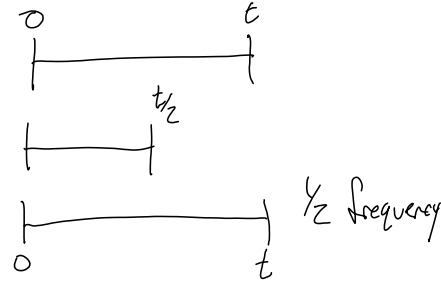
reduce power by reducing freq → longer to run program

reduce voltage → errors
 ↳ threshold voltage ~ 0.7V

fewer transistors
 ↳ C goes down → lower voltage slower transistors
 ↳ fewer "features" on chip

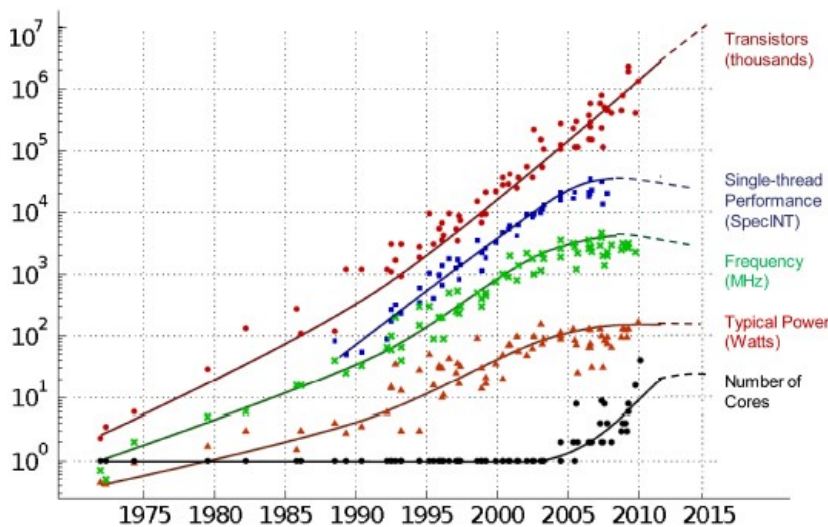
★ turn off early

Better instruction sets
 ↳ multiple things per cycle
 ↳ parallelism
 reduce freq



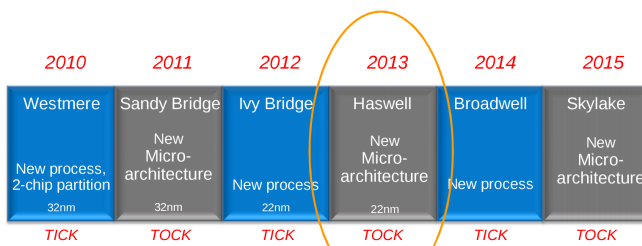
Trends

35 Years of Microprocessor Trend Data



Slides from Intel

Intel Tick-Tock Model



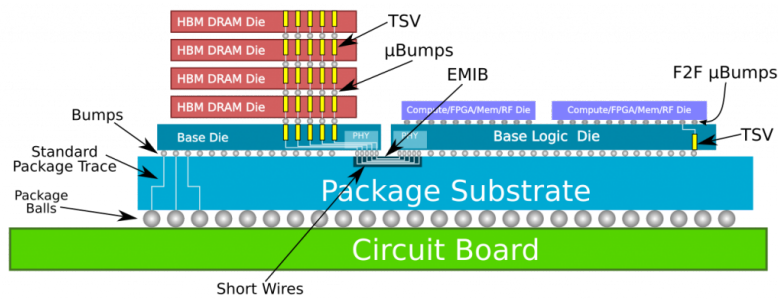
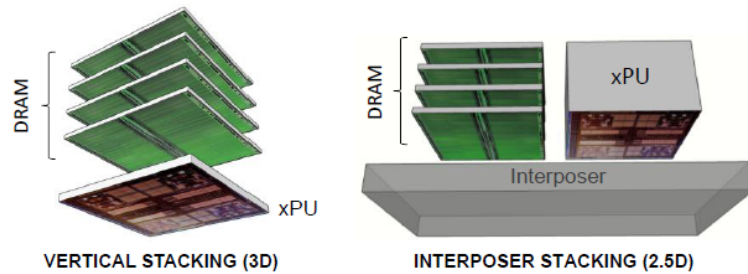
Tick-tock delivers leadership through technology innovation on a reliable and predictable timeline

Other trends

DIE STACKING IS IDEAL FOR INTEGRATION



- All they do is reduce metal interconnect by improving proximity of disparate technologies



[John Hennessy and David Patterson 2017 ACM A.M. Turing Award Lecture](#)

